

# SM72480 SolarMagic 1.6V, WSON-6 Factory Preset Temperature Switch and Temperature Sensor

Check for Samples: SM72480

#### **FEATURES**

- Renewable Energy Grade
- **Low 1.6V Operation**
- **Latching Function: Device Can Latch the Over Temperature Condition**
- **Push-pull and Open-Drain Temperature Switch Outputs**
- **Very Linear Analog V<sub>TEMP</sub> Temperature Sensor**
- **V<sub>TEMP</sub> Output Short-circuit Protected**
- 2.2 mm by 2.5 mm (typ) WSON-6 Package
- **Excellent Power Supply Noise Rejection**

#### APPLICATIONS

- PV Power Optimizers
- **Wireless Transceivers**
- **Battery Management**
- **Automotive**
- **Disk Drives**

#### **KEY SPECIFICATIONS**

- Supply Voltage 1.6V to 5.5V
- Supply Current 8 µA (typ)
- Accuracy, Trip Point Temperature 0°C to 150°C ±2.2°C
- Accuracy, VTEMP 0°C to 150°C ±2.3°C
- VTEMP Output Drive ±100 μA
- Operating Temperature -50°C to 150°C
- Hysteresis Temperature 4.5°C to 5.5°C

DESCRIPTION

The SM72480 is a low-voltage, precision, dual-output, low-power temperature switch and temperature sensor. The temperature trip point (T<sub>TRIP</sub>) is set at the factory to be 120°C. Built-in temperature hysteresis (T<sub>HYST</sub>) keeps the output stable in an environment of temperature instability.

In normal operation the SM72480 temperature switch outputs assert when the die temperature exceeds T<sub>TRIP</sub>. The temperature switch outputs will reset when the temperature falls below a temperature equal to  $(T_{TRIP} - T_{HYST})$ . The OVERTEMP digital output, is active-high with a push-pull structure, while the OVERTEMP digital output, is active-low with an opendrain structure.

The analog output, V<sub>TEMP</sub>, delivers an analog output voltage with Negative Temperature Coefficient -NTC.

Driving the TRIP TEST input high: (1) causes the digital outputs to be asserted for in-situ verification and, (2) causes the threshold voltage to appear at the V<sub>TEMP</sub> output pin, which could be used to verify the temperature trip point.

The SM72480's low minimum supply voltage makes it ideal for 1.8 volt system designs. Its wide operating range, low supply current, and excellent accuracy provide a temperature switch solution for a wide range of commercial and industrial applications.

### Connection Diagram

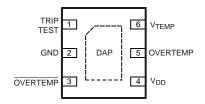


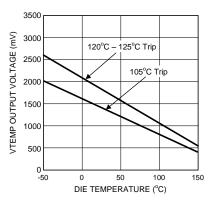
Figure 1. WSON-6 - Top View See Package Number NGF0006A

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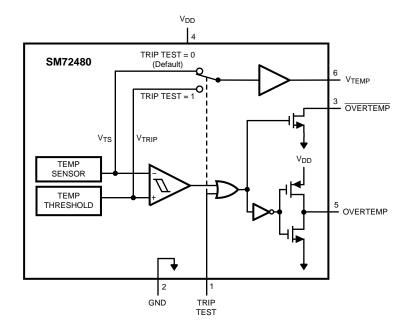


## **Typical Transfer Characteristic**

Figure 2. V<sub>TEMP</sub> Analog Voltage vs Die Temperature



### **Block Diagram**



### **PIN DESCRIPTIONS**

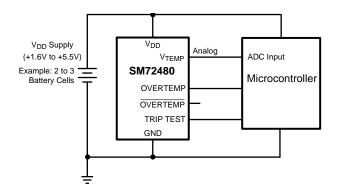
Pin No.	Name	Туре	Equivalent Circuit	Description
1	TRIP TEST	Digital Input	V <sub>DD</sub> 1 µA	TRIP TEST pin. Active High input. If TRIP TEST = 0 (Default) then: $V_{TEMP} = V_{TS}, \text{ Temperature Sensor Output Voltage}$ If TRIP TEST = 1 then: $OVERTEMP \text{ and } \overline{OVERTEMP} \text{ outputs are asserted and}$ $V_{TEMP} = V_{TRIP}, \text{ Temperature Trip Voltage}.$ This pin may be left open if not used.



### **PIN DESCRIPTIONS (continued)**

Pin No.	Name	Туре	Equivalent Circuit	Description
5	OVERTEMP	Digital Output	V <sub>DD</sub> GND	Over Temperature Switch output Active High, Push-Pull Asserted when the measured temperature exceeds the Trip Point Temperature or if TRIP TEST = 1 This pin may be left open if not used.
3	OVERTEMP	Digital Output	GND	Over Temperature Switch output Active Low, Open-drain (See OVERTEMP OPEN-DRAIN DIGITAL OUTPUT regarding required pull-up resistor.) Asserted when the measured temperature exceeds the Trip Point Temperature or if TRIP TEST = 1 This pin may be left open if not used.
6	V <sub>TEMP</sub>	Analog Output		
4	$V_{DD}$	Power	Positive Supply Voltage	
2	GND	Ground		Power Supply Ground
DAP	Die Attach Pad			The best thermal conductivity between the device and the PCB is achieved by soldering the DAP of the package to the thermal pad on the PCB. The thermal pad can be a floating node. However, for improved noise immunity the thermal pad should be connected to the circuit GND node, preferably directly to pin 2 (GND) of the device.

## **Typical Application**





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



### Absolute Maximum Ratings(1)

Supply Voltage		-0.3V to +6.0V		
Voltage at OVERTEMP pin		-0.3V to +6.0V		
Voltage at OVERTEMP and V <sub>TEMP</sub> pins		-0.3V to (V <sub>DD</sub> + 0.5V)		
TRIP TEST Input Voltage		-0.3V to (V <sub>DD</sub> + 0.5V)		
Output Current, any output pin		±7 mA		
Input Current at any pin (2)		5 mA		
Storage Temperature		−65°C to +150°C		
Maximum Junction Temperature	$T_{J(MAX)}$	+155°C		
ESD Susceptibility <sup>(3)</sup>	Human Body Model	4500V		
	300V			
	1000V			
For soldering specifications: see www.ti.c	om/lit/SNOA549	1		

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The ensured specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) When the input voltage (V<sub>I</sub>) at any pin exceeds power supplies (V<sub>I</sub> < GND or V<sub>I</sub> > V<sub>DD</sub>), the current at that pin should be limited to 5 mA.
- (3) The Human Body Model (HBM) is a 100 pF capacitor charged to the specified voltage then discharged through a 1.5 kΩ resistor into each pin. The Machine Model (MM) is a 200 pF capacitor charged to the specified voltage then discharged directly into each pin. The Charged Device Model (CDM) is a specified circuit characterizing an ESD event that occurs when a device acquires charge through some triboelectric (frictional) or electrostatic induction processes and then abruptly touches a grounded object or surface.

### Operating Ratings<sup>(1)</sup>

Specified Temperature Range		$T_{MIN} \le T_A \le T_{MAX}$
SM72480		-50°C ≤ T <sub>A</sub> ≤ +150°C
Supply Voltage Range (V <sub>DD</sub> )		+1.6 V to +5.5 V
Thermal Resistance (θ <sub>JA</sub> ) <sup>(2)(3)</sup>	WSON-6 (Package SDB06A)	152 °C/W

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The ensured specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) The junction to ambient temperature resistance  $(\theta_{JA})$  is specified without a heat sink in still air.
- (3) Changes in output due to self heating can be computed by multiplying the internal dissipation by the temperature resistance.

#### **Accuracy Characteristics Trip Point Accuracy**

Parameter	Conditi	ons	Limits <sup>(1)</sup>	Units (Limit)
Trip Point Accuracy <sup>(2)</sup>	0°C - 150°C	$V_{DD} = 5.0 \text{ V}$	±2.2	°C (max)

- (1) Limits are ensured to AOQL (Average Outgoing Quality Level).
- (2) Accuracy is defined as the error between the measured and reference output voltages, tabulated in the Conversion Table at the specified conditions of supply gain setting, voltage, and temperature (expressed in °C). Accuracy limits include line regulation within the specified conditions. Accuracy limits do not include load regulation; they assume no DC load.



### Accuracy Characteristics V<sub>TEMP</sub> Analog Temperature Sensor Output Accuracy

The limits do not include DC load regulation. The stated accuracy limits are with reference to the values in the SM72480 Conversion Table.

Parameter		Conditions		Limits <sup>(1)</sup>	Units (Limit)
		$T_A = 20$ °C to $40$ °C	$V_{DD} = 2.3 \text{ to } 5.5 \text{ V}$	±1.8	
		$T_A = 0$ °C to $70$ °C	V <sub>DD</sub> = 2.5 to 5.5 V	±2.0	
V <sub>TEMP</sub> Temperature	Trip Point 125°C or 120°C	$T_A = 0$ °C to 90°C	V <sub>DD</sub> = 2.5 to 5.5 V	±2.1	°C
Accuracy <sup>(2)</sup>		T <sub>A</sub> = 0°C to 120°C	V <sub>DD</sub> = 2.5 to 5.5 V	±2.2	(max) <sup>(2)</sup>
		T <sub>A</sub> = 0°C to 150°C	V <sub>DD</sub> = 2.5 to 5.5 V	±2.3	
		$T_A = -50$ °C to 0°C	$V_{DD} = 3.0 \text{ to } 5.5 \text{ V}$	±1.7	
		T <sub>A</sub> = 20°C to 40°C	V <sub>DD</sub> = 1.8 to 5.5 V	±1.8	
		$T_A = 0$ °C to $70$ °C	V <sub>DD</sub> = 1.9 to 5.5 V	±2.0	
V <sub>TEMP</sub> Temperature	Trip Point 105°C	$T_A = 0$ °C to 90°C	V <sub>DD</sub> = 1.9 to 5.5 V	±2.1	°C (max)
Accuracy		T <sub>A</sub> = 0°C to 120°C	V <sub>DD</sub> = 1.9 to 5.5 V	±2.2	
		$T_A = 0$ °C to 150°C	$V_{DD} = 1.9 \text{ to } 5.5 \text{ V}$	±2.3	
		$T_A = -50$ °C to 0°C	$V_{DD} = 2.3 \text{ to } 5.5 \text{ V}$	±1.7	

<sup>(1)</sup> Limits are ensured to AOQL (Average Outgoing Quality Level).

#### **Electrical Characteristics**

Unless otherwise noted, these specifications apply for  $+V_{DD} = +1.6V$  to +5.5V. Boldface limits apply for  $T_A = T_J = T_{MIN}$  to  $T_{MAX}$ ; all other limits  $T_A = T_J = 25$ °C.

Symbol	Parameter		Conditions	Typical <sup>(1)</sup>	Limits <sup>(2)</sup>	Units (Limit)
GENERAL	SPECIFICATIONS					
I <sub>S</sub>	Quiescent Power Supply Current			8	16	μA (max)
	Lluotoropio			5	5.5	°C (max)
	Hysteresis			5	4.5	°C (Min)
OVERTEN	MP DIGITAL OUTPUT	ACTIVE HIGH,	PUSH-PULL			
		V <sub>DD</sub> ≥ 1.6V	Source ≤ 340 µA			
	Lawia IId II Outrout Valtage	V <sub>DD</sub> ≥ 2.0V	Source ≤ 498 µA		$V_{DD}$ – 0.2 $V$	V (min)
\/		V <sub>DD</sub> ≥ 3.3V	Source ≤ 780 µA			
$V_{OH}$	Logic "1" Output Voltage	V <sub>DD</sub> ≥ 1.6V	Source ≤ 600 µA		V <sub>DD</sub> - 0.45V	
		V <sub>DD</sub> ≥ 2.0V	Source ≤ 980 µA			V (min)
		V <sub>DD</sub> ≥ 3.3V	Source ≤ 1.6 mA			
вотн оу	ERTEMP and OVERTEMP DIG	TAL OUTPUTS				
		V <sub>DD</sub> ≥ 1.6V	Sink ≤ 385 μA			
V <sub>OL</sub>		V <sub>DD</sub> ≥ 2.0V	Sink ≤ 500 μA		0.2	
		V <sub>DD</sub> ≥ 3.3V	Sink ≤ 730 μA			\/ ()
	Logic "0" Output Voltage	V <sub>DD</sub> ≥ 1.6V	Sink ≤ 690 μA			V (max)
		V <sub>DD</sub> ≥ 2.0V	Sink ≤ 1.05 mA		0.45	
		V <sub>DD</sub> ≥ 3.3V	Sink ≤ 1.62 mA			

<sup>(1)</sup> Typicals are at  $T_J = T_A = 25^{\circ}C$  and represent most likely parametric norm.

<sup>(2)</sup> Accuracy is defined as the error between the measured and reference output voltages, tabulated in the Conversion Table at the specified conditions of supply gain setting, voltage, and temperature (expressed in °C). Accuracy limits include line regulation within the specified conditions. Accuracy limits do not include load regulation; they assume no DC load.

<sup>(2)</sup> Limits are ensured to AOQL (Average Outgoing Quality Level).



### **Electrical Characteristics (continued)**

Unless otherwise noted, these specifications apply for  $+V_{DD} = +1.6V$  to +5.5V. Boldface limits apply for  $T_A = T_J = T_{MIN}$  to  $T_{MAX}$ ; all other limits  $T_A = T_J = 25$ °C.

Symbol	Parameter		Typical <sup>(1)</sup>	Limits <sup>(2)</sup>	Units (Limit)	
OVERTE	MP DIGITAL OUTPUT	ACTIVE LOW, OPE	N DRAIN			
	Logic "1" Output Leakage	T <sub>A</sub> = 30 °C		0.001	4	(
I <sub>OH</sub>	Current <sup>(3)</sup>	T <sub>A</sub> = 150 °C		0.025	1	μA (max)
V <sub>TEMP</sub> AN	ALOG TEMPERATURE SENSOR	OUTPUT				
	V <sub>TEMP</sub> Sensor Gain	Trip Point = 105°C		-7.7		mV/°C
		Trip Point = 125°C o	or 120°C	-10.3		mV/°C
		4.07/27/	Source $\leq 90 \mu A$ (V <sub>DD</sub> - V <sub>TEMP</sub> ) $\geq 200 \text{ mV}$	-0.1	-1	mV (max)
		1.6V ≤ V <sub>DD</sub> < 1.8V	Sink ≤ 100 μA V <sub>TEMP</sub> ≥ 260 mV	0.1	1	mV (max)
	V <sub>TEMP</sub> Load Regulation <sup>(4)</sup>	V > 4.0V	Source $\leq$ 120 $\mu$ A (V <sub>DD</sub> - V <sub>TEMP</sub> ) $\geq$ 200 mV	-0.1	-1	mV (max)
		V <sub>DD</sub> ≥ 1.8V	Sink ≤ 200 μA V <sub>TEMP</sub> ≥ 260 mV	0.1	1	mV (max)
		Source or Sink = 100 µA		1		Ohm
		V <sub>DD</sub> = +1.6V to +5.5V		0.29		mV
	V <sub>DD</sub> Supply- to-V <sub>TEMP</sub> DC Line Regulation <sup>(5)</sup>			74		μV/V
	Do Emo regulation			-82		dB
$C_L$	V <sub>TEMP</sub> Output Load Capacitance	Without series resistor. See CAPACITIVE LOADS.		1100		pF (max)
TRIP TES	T DIGITAL INPUT					•
V <sub>IH</sub>	Logic "1" Threshold Voltage				V <sub>DD</sub> - 0.5	V (min)
V <sub>IL</sub>	Logic "0" Threshold Voltage				0.5	V (max)
I <sub>IH</sub>	Logic "1" Input Current			1.5	2.5	μA (max)
I <sub>IL</sub>	Logic "0" Input Current (3)			0.001	1	μA (max)
TIMING						
t <sub>EN</sub>	Time from Power On to Digital Output Enabled. See definition below.			1.1	2.3	ms (max)
t <sub>V</sub>	Time from Power On to Analog Temperature Valid. See definition below.	$V_{TEMP} C_L = 0 pF to$	1100 pF	1.0	2.9	ms (max)

<sup>(3)</sup> The 1 µA limit is based on a testing limitation and does not reflect the actual performance of the part. Expect to see a doubling of the current for every 15°C increase in temperature. For example, the 1 nA typical current at 25°C would increase to 16 nA at 85°C.

<sup>(4)</sup> Source currents are flowing out of the SM72480. Sink currents are flowing into the SM72480.

<sup>(5)</sup> Line regulation (DC) is calculated by subtracting the output voltage at the highest supply voltage from the output voltage at the lowest supply voltage. The typical DC line regulation specification does not include the output voltage shift discussed in VOLTAGE SHIFT.



### Definitions of $t_{EN}$ and $t_{V}$

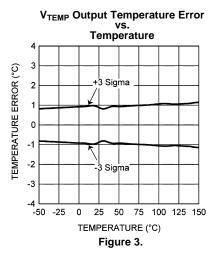


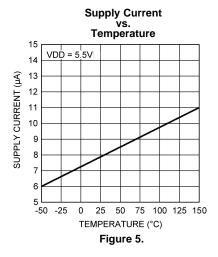
The curves shown represent typical performance under worst-case conditions. Performance improves with larger overhead ( $V_{DD} - V_{TEMP}$ ), larger  $V_{DD}$ , and lower temperatures.

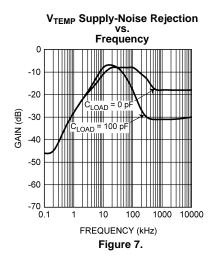
The curves shown represent typical performance under worst-case conditions. Performance improves with larger  $V_{TEMP}$ , larger  $V_{DD}$  and lower temperatures.

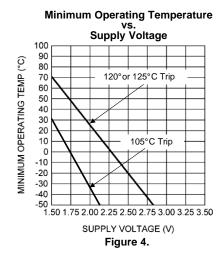


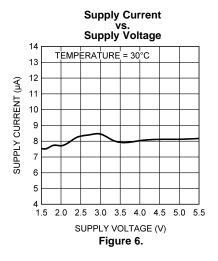
### **Typical Performance Characteristics**

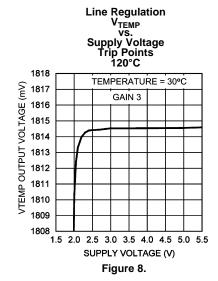














### SM72480 V<sub>TEMP</sub> VS DIE TEMPERATURE CONVERSION TABLE

The SM72480 has a factory-set gain, which is dependent on the Temperature Trip Point. The  $V_{TEMP}$  temperature sensor voltage, in millivolts, at each discrete die temperature over the complete operating range is shown in the conversion table below.

Table 1. V<sub>TEMP</sub> Temperature Sensor Output Voltage vs Die Temperature Conversion Table<sup>(1)</sup>

Die Temp.,	V <sub>TEMP</sub> , Analog Output Voltage, mV			
°C	T <sub>TRIP</sub> = 125 or 120°C	T <sub>TRIP</sub> = 105°C		
-50	2623	1967		
-49	2613	1960		
-48	2603	1952		
-47	2593	1945		
-46	2583	1937		
-45	2573	1930		
-44	2563	1922		
-43	2553	1915		
-42	2543	1908		
-41	2533	1900		
-40	2523	1893		
-39	2513	1885		
-38	2503	1878		
-37	2493	1870		
-36	2483	1863		
-35	2473	1855		
-34	2463	1848		
-33	2453	1840		
-32	2443	1833		
-31	2433	1825		
-30	2423	1818		
-29	2413	1810		
-28	2403	1803		
-27	2393	1795		
-26	2383	1788		
-25	2373	1780		
-24	2363	1773		
-23	2353	1765		
-22	2343	1757		
-21	2333	1750		
-20	2323	1742		
-19	2313	1735		
-18	2303	1727		
-17	2293	1720		
-16	2283	1712		
-15	2272	1705		
-14	2262	1697		
-13	2252	1690		
-12	2242	1682		

The V<sub>TEMP</sub> temperature sensor output voltage, in mV, vs Die Temperature, in °C for the gain corresponding to the temperature trip point. V<sub>DD</sub> = 5.0V.



# Table 1. V<sub>TEMP</sub> Temperature Sensor Output Voltage vs Die Temperature Conversion Table<sup>(1)</sup> (continued)

Die Temp.,	V <sub>TEMP</sub> , Analog Output Voltage, mV			
°C ' ´	T <sub>TRIP</sub> = 125 or 120°C	T <sub>TRIP</sub> = 105°C		
<b>-11</b>	2232	1674		
<b>-10</b>	2222	1667		
-9	2212	1659		
-8	2202	1652		
<b>-</b> 7	2192	1644		
-6	2182	1637		
<b>-</b> 5	2171	1629		
-4	2161	1621		
-3	2151	1614		
-2	2141	1606		
-1	2131	1599		
0	2121	1591		
1	2111	1583		
2	2101	1576		
3	2090	1568		
4	2080	1561		
5	2070	1553		
6	2060	1545		
7				
	2050	1538		
8	2040	1530		
9	2029	1522		
10	2019	1515		
11	2009	1507		
12	1999	1499		
13	1989	1492		
14	1978	1484		
15	1968	1477		
16	1958	1469		
17	1948	1461		
18	1938	1454		
19	1927	1446		
20	1917	1438		
21	1907	1431		
22	1897	1423		
23	1886	1415		
24	1876	1407		
25	1866	1400		
26	1856	1392		
27	1845	1384		
28	1835	1377		
29	1825	1369		
30	1815	1361		
31	1804	1354		
32	1794	1346		
33	1784	1338		
34	1774	1331		



Table 1. V<sub>TEMP</sub> Temperature Sensor Output Voltage vs Die Temperature Conversion Table<sup>(1)</sup> (continued)

Die Temp.,	V <sub>TEMP</sub> , Analog Output Voltage, mV		
°C	T <sub>TRIP</sub> = 125 or 120°C	T <sub>TRIP</sub> = 105°C	
35	1763	1323	
36	1753	1315	
37	1743	1307	
38	1732	1300	
39	1722	1292	
40	1712	1284	
41	1701	1276	
42	1691	1269	
43	1681	1261	
44	1670	1253	
45	1660	1245	
46	1650	1238	
47	1639	1230	
48	1629	1222	
49	1619	1214	
50	1608	1207	
51	1598	1199	
52	1588	1191	
53	1577	1183	
54	1567	1176	
55	1557	1168	
56	1546	1160	
57	1536	1152	
58	1525	1144	
59	1515	1137	
60	1505	1129	
61	1494	1121	
62	1484	1113	
63	1473	1105	
64	1463	1098	
65	1453	1090	
66	1442	1082	
67	1432	1074	
68	1421	1066	
69	1411	1059	
70	1400	1051	
71	1390	1043	
72	1380	1035	
73	1369	1027	
74	1359	1019	
75	1348	1012	
76	1338	1004	
77	1327	996	
78	1317	988	
79	1306	980	
80	1296	972	



# Table 1. V<sub>TEMP</sub> Temperature Sensor Output Voltage vs Die Temperature Conversion Table<sup>(1)</sup> (continued)

Die Temp., °C	V <sub>TEMP</sub> , Analog Output Voltage, mV			
°C	T <sub>TRIP</sub> = 125 or 120°C	T <sub>TRIP</sub> = 105°C		
81	1285	964		
82	1275	957		
83	1264	949		
84	1254	941		
85	1243	933		
86	1233	925		
87	1222	917		
88	1212	909		
89	1201	901		
90	1191	894		
91	1180	886		
92	1170	878		
93	1159	870		
94	1149	862		
95	1138	854		
96	1128	846		
97	1117	838		
98	1106	830		
99	1096	822		
100	1085	814		
101	1075	807		
102	1064	799		
103	1054	791		
104	1043	783		
105	1032	775		
106	1022	767		
107	1011	759		
108	1001	751		
109	990	743		
110	979	735		
111	969	727		
112	958	719		
113	948	711		
114	937	703		
115	926	695		
116	916	687		
117	905	679		
118	894	671		
119	884	663		
120	873	655		
121	862	647		
122	852	639		
123	841	631		
124	831	623		
125	820	615		
126	809	607		

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Table 1. V<sub>TEMP</sub> Temperature Sensor Output Voltage vs Die Temperature Conversion Table<sup>(1)</sup> (continued)

Die Temp.,	V <sub>TEMP</sub> , Analog Output Voltage, mV						
°C '	T <sub>TRIP</sub> = 125 or 120°C	T <sub>TRIP</sub> = 105°C					
127	798	599					
128	788	591					
129	777	583					
130	766	575					
131	756	567					
132	745	559					
133	734	551					
134	724	543					
135	713	535					
136	702	527					
137	691	519					
138	681	511					
139	670	503					
140	659	495					
141	649	487					
142	638	479					
143	627	471					
144	616	463					
145	606	455					
146	595	447					
147	584	438					
148	573	430					
149	562	422					
150	552	414					

### **V<sub>TEMP</sub> vs DIE TEMPERATURE APPROXIMATIONS**

The SM72480's  $V_{\mathsf{TEMP}}$  analog temperature output is very linear. The Conversion Table above and the equation in The Second-Order Equation (Parabolic) represent the most accurate typical performance of the  $V_{\mathsf{TEMP}}$  voltage output vs Temperature.

### The Second-Order Equation (Parabolic)

The data from the Conversion Table, or the equation below, when plotted, has an umbrella-shaped parabolic curve.  $V_{TEMP}$  is in mV.

$$V_{(\text{TEMP}=120 \text{ or } 125)} = 1814.6 - 10.270 \text{ x } (T_{\text{DIE}} - 30^{\circ}\text{C}) - 2.12\text{e-}3 \text{ x } (T_{\text{DIE}} - 30^{\circ}\text{C})^{2}$$

$$V_{(\text{TEMP}=105)} = 1361.4 - 7.701 \text{ x } (T_{\text{DIE}} - 30^{\circ}\text{C}) - 1.60\text{e-}3 \text{ x } (T_{\text{DIE}} - 30^{\circ}\text{C})^{2}$$
(1)

#### The First-Order Approximation (Linear)

For a quicker approximation, although less accurate than the second-order, over the full operating temperature range the linear formula below can be used. Using this formula, with the constant and slope in the following set of equations, the best-fit  $V_{\text{TEMP}}$  vs Die Temperature performance can be calculated with an approximation error less than 18 mV.  $V_{\text{TEMP}}$  is in mV.

$$V_{\text{(TEMP=120 or 125)}} = 2119 - 10.36 \times T_{\text{DIE}}$$

$$V_{\text{(TEMP=105)}} = 1590 - 7.77 \times T_{\text{DIE}}$$
(2)



#### First-Order Approximation (Linear) over Small Temperature Range

For a linear approximation, a line can easily be calculated over the desired temperature range from the Conversion Table using the two-point equation:

$$V - V_1 = \left(\frac{V_2 - V_1}{T_2 - T_1}\right) \times (T - T_1)$$
(3)

Where V is in mV, T is in  ${}^{\circ}$ C, T<sub>1</sub> and V<sub>1</sub> are the coordinates of the lowest temperature, T<sub>2</sub> and V<sub>2</sub> are the coordinates of the highest temperature.

$$V - 2396 \text{ mV} = (-12.8 \text{ mV/C}) \times (T - 20^{\circ}C)$$
 (4)

$$V = (-12.8 \text{ mV/C}) \times (T-20\text{C}) + 2396 \text{ mV}$$
 (5)

Using this method of linear approximation, the transfer function can be approximated for one or more temperature ranges of interest.

### **OVERTEMP and OVERTEMP Digital Outputs**

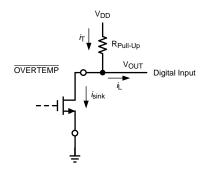
The OVERTEMP Active High, Push-Pull Output and the OVERTEMP Active Low, Open-Drain Output both assert at the same time whenever the Die Temperature reaches the factory preset Temperature Trip Point. They also assert simultaneously whenever the TRIP TEST pin is set high. Both outputs de-assert when the die temperature goes below the Temperature Trip Point - Hysteresis. These two types of digital outputs enable the user the flexibility to choose the type of output that is most suitable for his design.

Either the OVERTEMP or the OVERTEMP Digital Output pins can be left open if not used.

#### **OVERTEMP OPEN-DRAIN DIGITAL OUTPUT**

The  $\overline{\text{OVERTEMP}}$  Active Low, Open-Drain Digital Output, if used, requires a pull-up resistor between this pin and  $V_{DD}$ . The following section shows how to determine the pull-up resistor value.

Figure 9. Determining the Pull-up Resistor Value



The Pull-up resistor value is calculated at the condition of maximum total current,  $i_T$ , through the resistor. The total current is:

 $i_T = i_L + i_{sink}$ 

#### where

- i<sub>T</sub> is the maximum total current through the Pull-up Resistor at V<sub>OL</sub>.
- i<sub>1</sub> is the load current, which is very low for typical digital inputs.
- V<sub>OUT</sub> is the Voltage at the OVERTEMP pin. Use V<sub>OL</sub> for calculating the Pull-up resistor.
- V<sub>DD(Max)</sub> is the maximum power supply voltage to be used in the customer's system.

The pull-up resistor maximum value can be found by using the following formula:

$$R_{\text{pull-up}} = \frac{V_{\text{DD (Max)}} - V_{\text{OL}}}{i_{\text{T}}}$$
(7)

### **EXAMPLE CALCULATION**

Suppose we have, for our example, a  $V_{DD}$  of 3.3 V  $\pm$  0.3V, a CMOS digital input as a load, a  $V_{OL}$  of 0.2 V.

Product Folder Links: SM72480

(6)

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- 1. We see that for  $V_{OL}$  of 0.2 V the electrical specification for  $\overline{OVERTEMP}$  shows a maximim  $i_{sink}$  of 385  $\mu$ A.
- 2. Let  $i_L$ = 1  $\mu$ A, then  $i_T$  is about 386  $\mu$ A max. If we select 35  $\mu$ A as the current limit then  $i_T$  for the calculation becomes 35  $\mu$ A
- 3. We notice that  $V_{DD(Max)}$  is 3.3V + 0.3V = 3.6V and then calculate the pull-up resistor as  $R_{Pull-up} = (3.6 0.2)/35 \,\mu\text{A} = 97k$
- 4. Based on this calculated value, we select the closest resistor value in the tolerance family we are using.

In our example, if we are using 5% resistor values, then the next closest value is 100 kΩ.

#### **NOISE IMMUNITY**

The SM72480 is virtually immune from false triggers on the OVERTEMP and  $\overline{\text{OVERTEMP}}$  digital outputs due to noise on the power supply. Test have been conducted showing that, with the die temperature within 0.5°C of the temperature trip point, and the severe test of a 3 Vpp square wave "noise" signal injected on the V<sub>DD</sub> line, over the V<sub>DD</sub> range of 2V to 5V, there were no false triggers.

### **TRIP TEST Digital Input**

The TRIP TEST pin simply provides a means to test the OVERTEMP and OVERTEMP digital outputs electronically by causing them to assert, at any operating temperature, as a result of forcing the TRIP TEST pin high.

When the TRIP TEST pin is pulled high the  $V_{TEMP}$  pin will be at the  $V_{TRIP}$  voltage.

If not used, the TRIP TEST pin may either be left open or grounded.

### **V<sub>TEMP</sub> Analog Temperature Sensor Output**

The  $V_{\text{TEMP}}$  push-pull output provides the ability to sink and source significant current. This is beneficial when, for example, driving dynamic loads like an input stage on an analog-to-digital converter (ADC). In these applications the source current is required to quickly charge the input capacitor of the ADC. See the Applications Circuits section for more discussion of this topic. The SM72480 is ideal for this and other applications which require strong source or sink current.

#### **NOISE CONSIDERATIONS**

The SM72480's supply-noise rejection (the ratio of the AC signal on  $V_{\text{TEMP}}$  to the AC signal on  $V_{\text{DD}}$ ) was measured during bench tests. It's typical attenuation is shown in the Typical Performance Characteristics section. A load capacitor on the output can help to filter noise.

For operation in very noisy environments, some bypass capacitance should be present on the supply within approximately 2 inches of the SM72480.

#### **CAPACITIVE LOADS**

The  $V_{TEMP}$  Output handles capacitive loading well. In an extremely noisy environment, or when driving a switched sampling input on an ADC, it may be necessary to add some filtering to minimize noise coupling. Without any precautions, the  $V_{TEMP}$  can drive a capacitive load less than or equal to 1100 pF as shown in Figure 10. For capacitive loads greater than 1100 pF, a series resistor is required on the output, as shown in Figure 11, to maintain stable conditions.

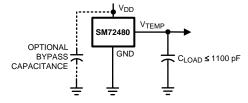
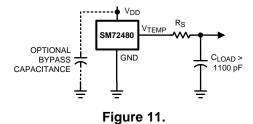


Figure 10. SM72480 No Decoupling Required for Capacitive Loads Less than 1100 pF.





C <sub>LOAD</sub>	Minimum R <sub>S</sub>
1.1 nF to 99 nF	3 kΩ
100 nF to 999 nF	1.5 kΩ
1 μF	800 Ω

#### **VOLTAGE SHIFT**

The SM72480 is very linear over temperature and supply voltage range. Due to the intrinsic behavior of an NMOS/PMOS rail-to-rail buffer, a slight shift in the output can occur when the supply voltage is ramped over the operating range of the device. The location of the shift is determined by the relative levels of  $V_{DD}$  and  $V_{TEMP}$ . The shift typically occurs when  $V_{DD} - V_{TEMP} = 1.0V$ .

This slight shift (a few millivolts) takes place over a wide change (approximately 200 mV) in V<sub>DD</sub> or V<sub>TEMP</sub>. Since the shift takes place over a wide temperature change of 5°C to 20°C, V<sub>TEMP</sub> is always monotonic. The accuracy specifications in the Electrical Characteristics table already includes this possible shift.

### **Mounting and Temperature Conductivity**

The SM72480 can be applied easily in the same way as other integrated-circuit temperature sensors. It can be glued or cemented to a surface.

The best thermal conductivity between the device and the PCB is achieved by soldering the DAP of the package to the thermal pad on the PCB. The temperatures of the lands and traces to the other leads of the SM72480 will also affect the temperature reading.

Alternatively, the SM72480 can be mounted inside a sealed-end metal tube, and can then be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the SM72480 and accompanying wiring and circuits must be kept insulated and dry, to avoid leakage and corrosion. This is especially true if the circuit may operate at cold temperatures where condensation can occur. If moisture creates a short circuit from the  $V_{TEMP}$  output to ground or  $V_{DD}$ , the  $V_{TEMP}$  output from the SM72480 will not be correct. Printed-circuit coatings are often used to ensure that moisture cannot corrode the leads or circuit traces.

The thermal resistance junction-to-ambient  $(\theta_{JA})$  is the parameter used to calculate the rise of a device junction temperature due to its power dissipation. The equation used to calculate the rise in the SM72480's die temperature is

$$T_{J} = T_{A} + \theta_{JA} \left[ (V_{DD}I_{Q}) + (V_{DD} - V_{TEMP}) I_{L} \right]$$
(8)

where  $T_A$  is the ambient temperature,  $I_Q$  is the quiescent current,  $I_L$  is the load current on the output, and  $V_O$  is the output voltage. For example, in an application where  $T_A = 30$  °C,  $V_{DD} = 5$  V,  $I_{DD} = 9$   $\mu A$ , Gain 4,  $V_{TEMP} = 2231$  mV, and  $I_L = 2$   $\mu A$ , the junction temperature would be 30.021 °C, showing a self-heating error of only 0.021 °C. Since the SM72480's junction temperature is the actual temperature being measured, care should be taken to minimize the load current that the  $V_{TEMP}$  output is required to drive. If The OVERTEMP output is used with a 100 k pull-up resistor, and this output is asserted (low), then for this example the additional contribution is [(152° C/W)x(5V)²/100k] = 0.038°C for a total self-heating error of 0.059°C. Table 2 shows the thermal resistance of the SM72480.



#### Table 2. SM72480 Thermal Resistance

Device Number		Package Number	Thermal Resistance (θ <sub>JA</sub> )	
	SM72480SD	SDB06A	152° C/W	

### **Applications Circuits**

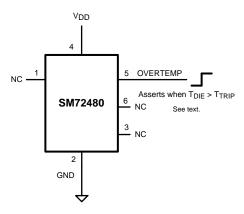


Figure 12. Temperature Switch Using Push-Pull Output

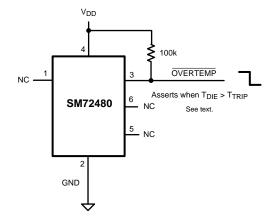


Figure 13. Temperature Switch Using Open-Drain Output

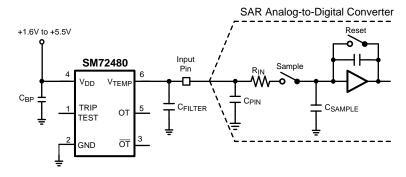


Figure 14. Suggested Connection to a Sampling Analog-to-Digital Converter Input Stage



Most CMOS ADCs found in microcontrollers and ASICs have a sampled data comparator input structure. When the ADC charges the sampling cap, it requires instantaneous charge from the output of the analog source such as the SM72480 temperature sensor and many op amps. This requirement is easily accommodated by the addition of a capacitor ( $C_{\text{FILTER}}$ ). The size of  $C_{\text{FILTER}}$  depends on the size of the sampling capacitor and the sampling frequency. Since not all ADCs have identical input stages, the charge requirements will vary. This general ADC application is shown as an example only.

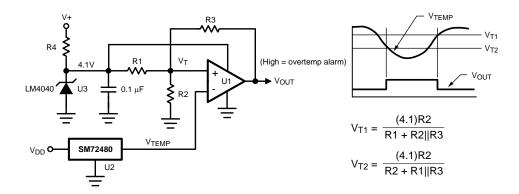


Figure 15. Celsius Temperature Switch

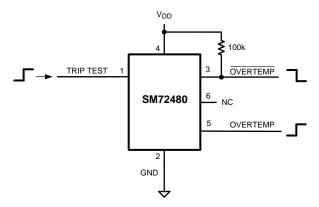


Figure 16. TRIP TEST Digital Output Test Circuit



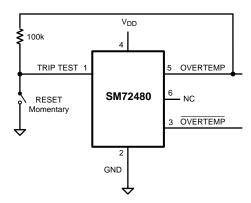


Figure 17. Latch Circuit using OVERTEMP Output

The TRIP TEST pin, normally used to check the operation of the OVERTEMP and OVERTEMP pins, may be used to latch the outputs whenever the temperature exceeds the programmed limit and causes the digital outputs to assert. As shown in the figure, when OVERTEMP goes high the TRIP TEST input is also pulled high and causes OVERTEMP output to latch high and the OVERTEMP output to latch low. The latch can be released by either momentarily pulling the TRIP TEST pin low (GND), or by toggling the power supply to the device. The resistor limits the current out of the OVERTEMP output pin.



### **REVISION HISTORY**

Cł	nanges from Revision B (April 2013) to Revision C	Pa	ge
•	Changed layout of National Data Sheet to TI format		19

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
SM72480SD-105/NOPB	Last Time Buy	Production	WSON (NGF)   6	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	701
SM72480SD-120/NOPB	Active	Production	WSON (NGF)   6	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	S80
SM72480SD-120/NOPB.A	Active	Production	WSON (NGF)   6	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	S80
SM72480SD-125/NOPB	Active	Production	WSON (NGF)   6	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	299
SM72480SD-125/NOPB.A	Active	Production	WSON (NGF)   6	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	299
SM72480SDE-105/NOPB	Last Time Buy	Production	WSON (NGF)   6	250   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	701
SM72480SDE-120/NO.A	NRND	Production	WSON (NGF)   6	250   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	S80
SM72480SDE-120/NOPB	NRND	Production	WSON (NGF)   6	250   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	S80
SM72480SDE-125/NO.A	NRND	Production	WSON (NGF)   6	250   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	299
SM72480SDE-125/NOPB	NRND	Production	WSON (NGF)   6	250   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	299
SM72480SDX-105/NOPB	Last Time Buy	Production	WSON (NGF)   6	4500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	701
SM72480SDX-120/NO.A	NRND	Production	WSON (NGF)   6	4500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	S80
SM72480SDX-120/NOPB	NRND	Production	WSON (NGF)   6	4500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	S80
SM72480SDX-125/NO.A	NRND	Production	WSON (NGF)   6	4500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	299
SM72480SDX-125/NOPB	NRND	Production	WSON (NGF)   6	4500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-50 to 150	299

<sup>(1)</sup> **Status:** For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



### **PACKAGE OPTION ADDENDUM**

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(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

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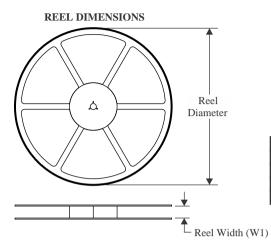
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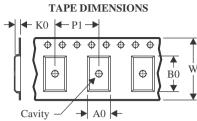
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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

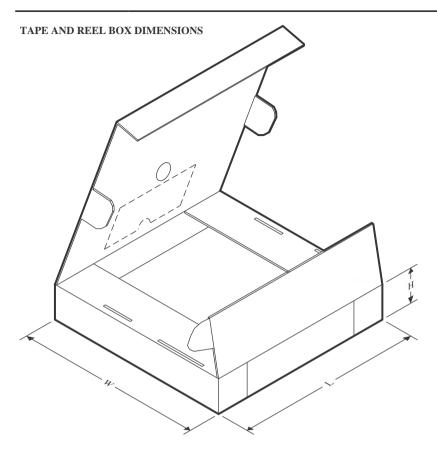


#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SM72480SD-105/NOPB	WSON	NGF	6	1000	177.8	12.4	2.8	2.5	1.0	8.0	12.0	Q1
SM72480SD-120/NOPB	WSON	NGF	6	1000	177.8	12.4	2.8	2.5	1.0	8.0	12.0	Q1
SM72480SD-125/NOPB	WSON	NGF	6	1000	177.8	12.4	2.8	2.5	1.0	8.0	12.0	Q1
SM72480SDE-105/NOPB	WSON	NGF	6	250	177.8	12.4	2.8	2.5	1.0	8.0	12.0	Q1
SM72480SDE-120/NOPB	WSON	NGF	6	250	177.8	12.4	2.8	2.5	1.0	8.0	12.0	Q1
SM72480SDE-125/NOPB	WSON	NGF	6	250	177.8	12.4	2.8	2.5	1.0	8.0	12.0	Q1
SM72480SDX-105/NOPB	WSON	NGF	6	4500	330.0	12.4	2.8	2.5	1.0	8.0	12.0	Q1
SM72480SDX-120/NOPB	WSON	NGF	6	4500	330.0	12.4	2.8	2.5	1.0	8.0	12.0	Q1
SM72480SDX-125/NOPB	WSON	NGF	6	4500	330.0	12.4	2.8	2.5	1.0	8.0	12.0	Q1

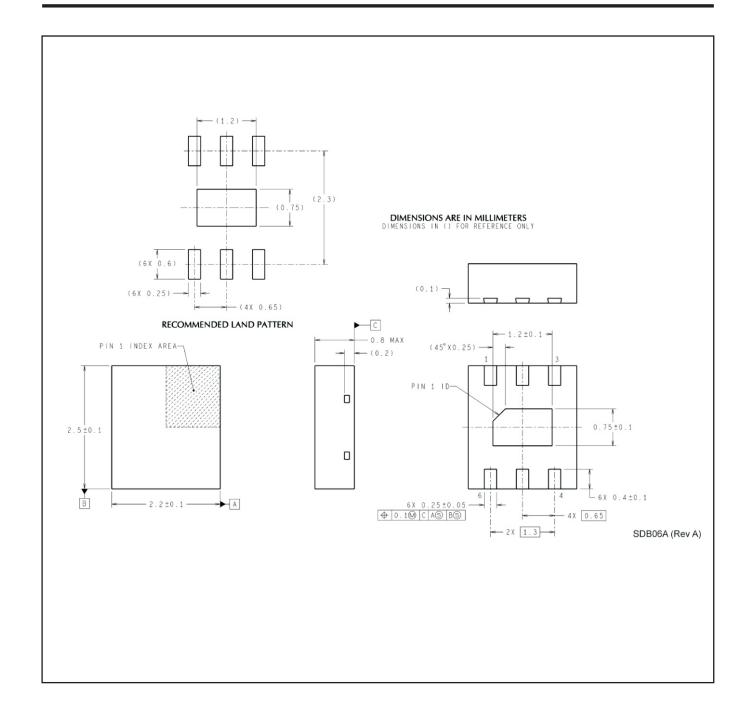


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\*All dimensions are nominal

All difficultions are norminal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SM72480SD-105/NOPB	WSON	NGF	6	1000	208.0	191.0	35.0
SM72480SD-120/NOPB	WSON	NGF	6	1000	208.0	191.0	35.0
SM72480SD-125/NOPB	WSON	NGF	6	1000	208.0	191.0	35.0
SM72480SDE-105/NOPB	WSON	NGF	6	250	208.0	191.0	35.0
SM72480SDE-120/NOPB	WSON	NGF	6	250	208.0	191.0	35.0
SM72480SDE-125/NOPB	WSON	NGF	6	250	208.0	191.0	35.0
SM72480SDX-105/NOPB	WSON	NGF	6	4500	367.0	367.0	35.0
SM72480SDX-120/NOPB	WSON	NGF	6	4500	367.0	367.0	35.0
SM72480SDX-125/NOPB	WSON	NGF	6	4500	367.0	367.0	35.0



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